

REV	DATE	ECN NO.	MODIFICATION	APPROVER
A	2016/10/14		NEW	Jason_Lee
A1	2017/05/15	RD00317051501	SIZE CHANGE	Jason_Lee

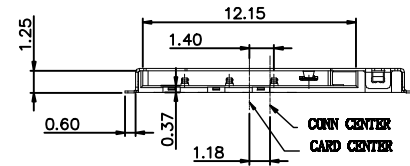
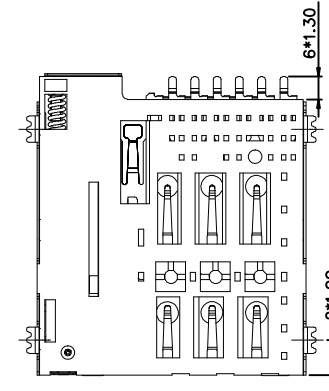
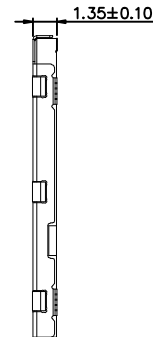
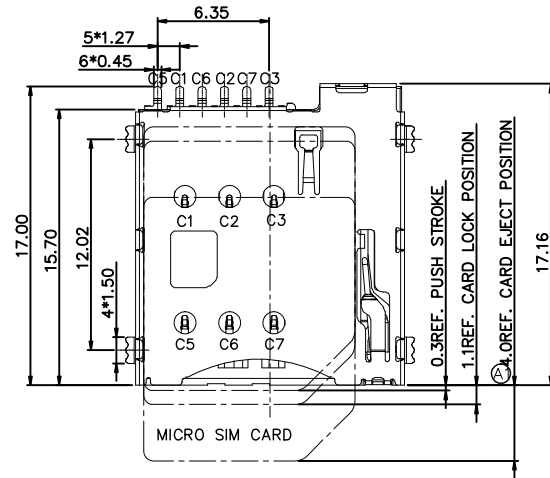
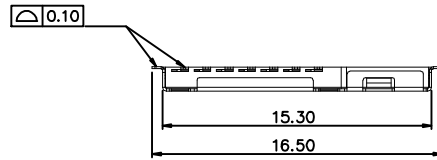
NOTES:

MATERIAL:

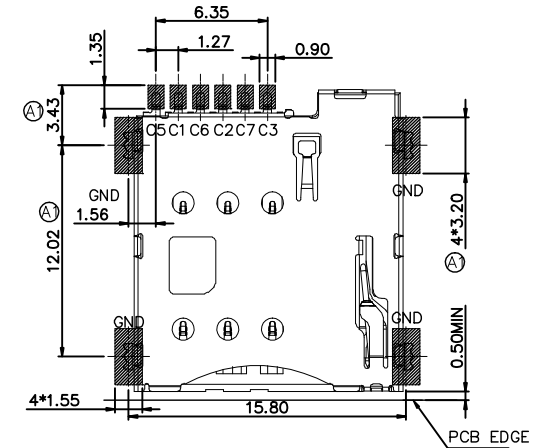
Housing: High Temperature thermoplastic,UL94V-0
Terminal: Copper Alloy
Shell: Stainless

SPECIALITY:

Rated Current:0.5A MAX
Rated Voltage:50V
Ambient Temperature Range: -40℃~+85℃
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100mΩ Max
Insulation Resistance:1000MΩ/250V DC
Dielectric Withstanding Voltage:500V AC
Durability:5000 cycles
Temperature 260±5℃,



IM pin Assignment	
IN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

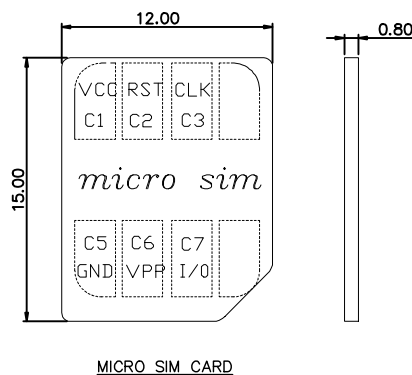


■ SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES
IN THE LAYOUT SPACE OF THE PRODUCTS

RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE±0.05



GENERAL TOLERANCE				UNITS		NAME: MICRO SIM CARD 6P PUSH PUSH		ATOM® 深圳市爱特姆科技有限公司 SHENZHEN ATOM TECHNOLOGY CO., LTD.			
SELECT	TOL.	1	2	3	MAT'L	PART NO:	SI63C-01200	TITLE: MICRO SIM CARD 6P PUSH PUSH SMT H=1.35mm 不带检测脚 无柱			
X.XXX	±0.10±0.05±0.15				FINISH	APPD:		DWG NO. ATOM-A03338			
X.XX	±0.15±0.13±0.25					CHKD:					
X.X	±0.20±0.25±0.5					DR:	JACK				
X.	±0.30±0.38±1.00										
ANGLE	±2'				Q'TY						